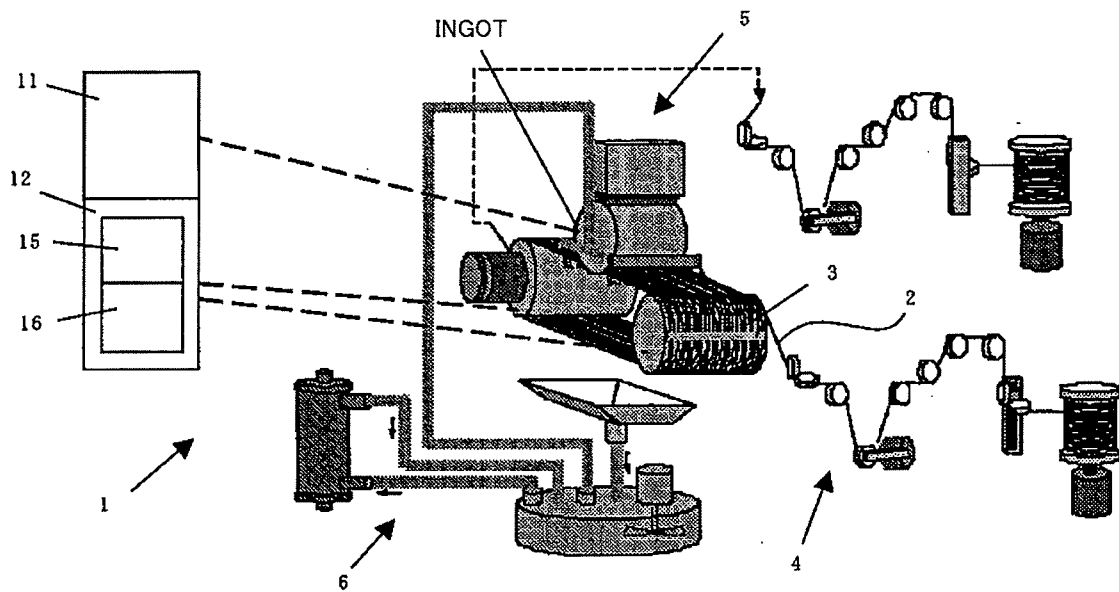
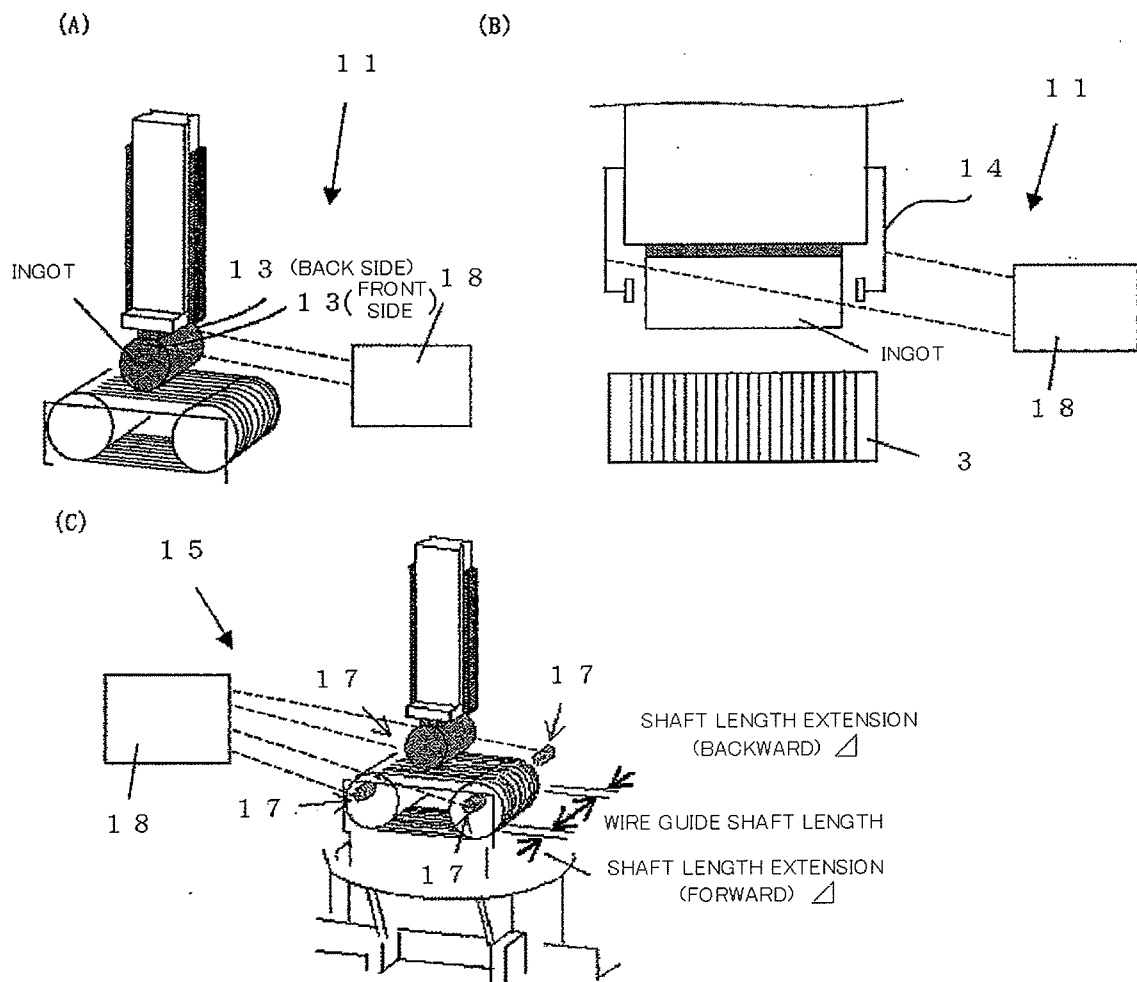


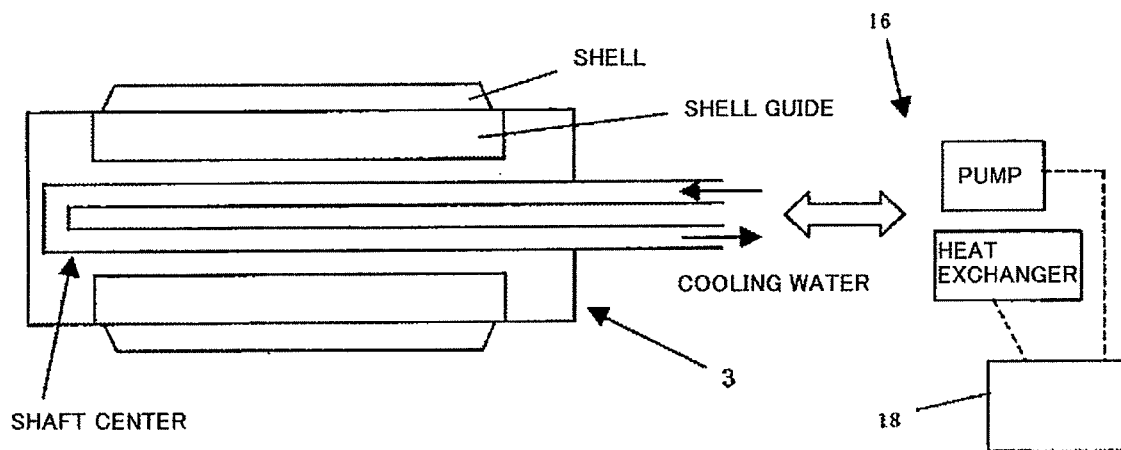
[FIG. 1]



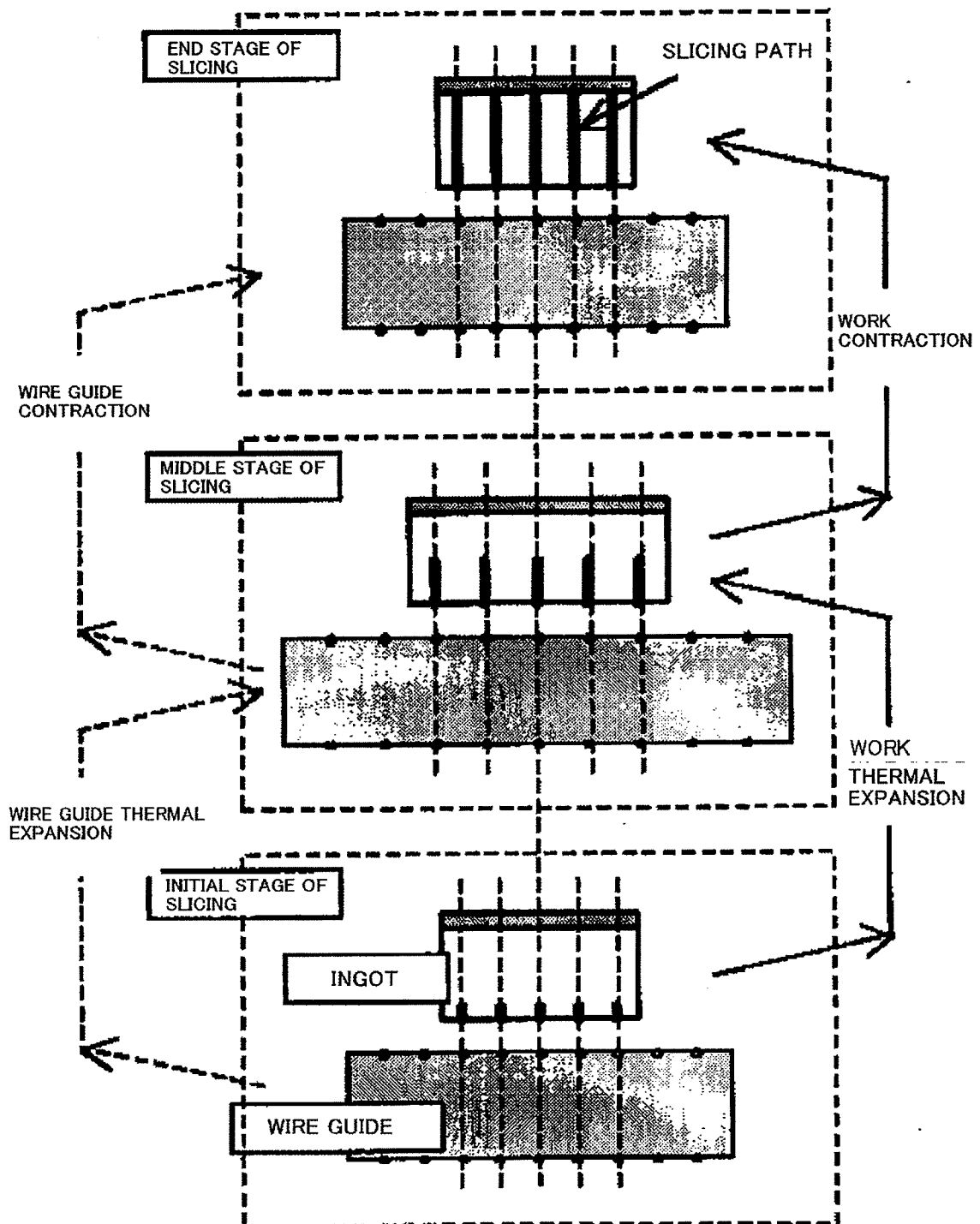
[FIG. 2]



[FIG. 3]

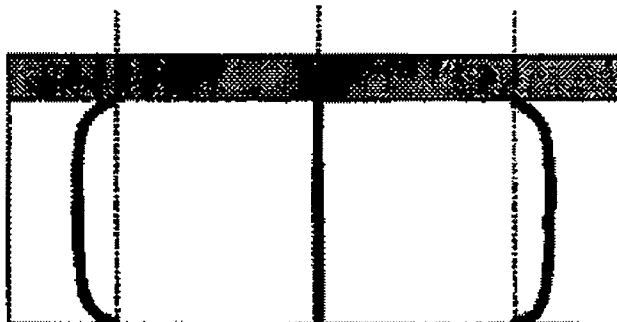


[FIG. 4]

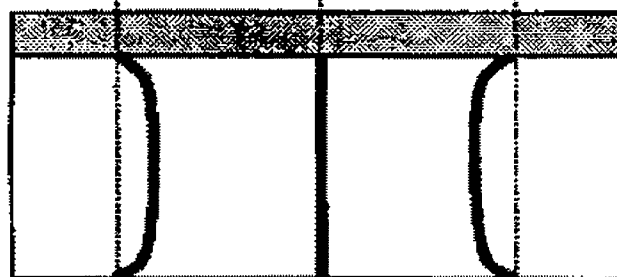


[FIG. 5]

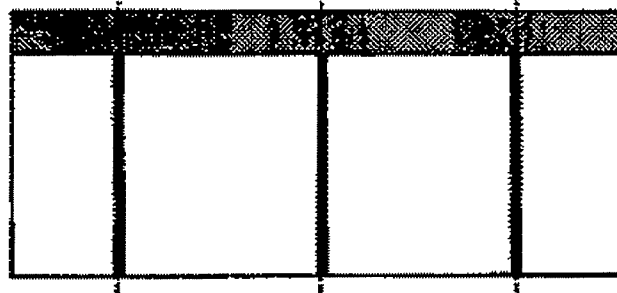
INFLUENCE OF WIRE GUIDE
THERMAL EXPANSION



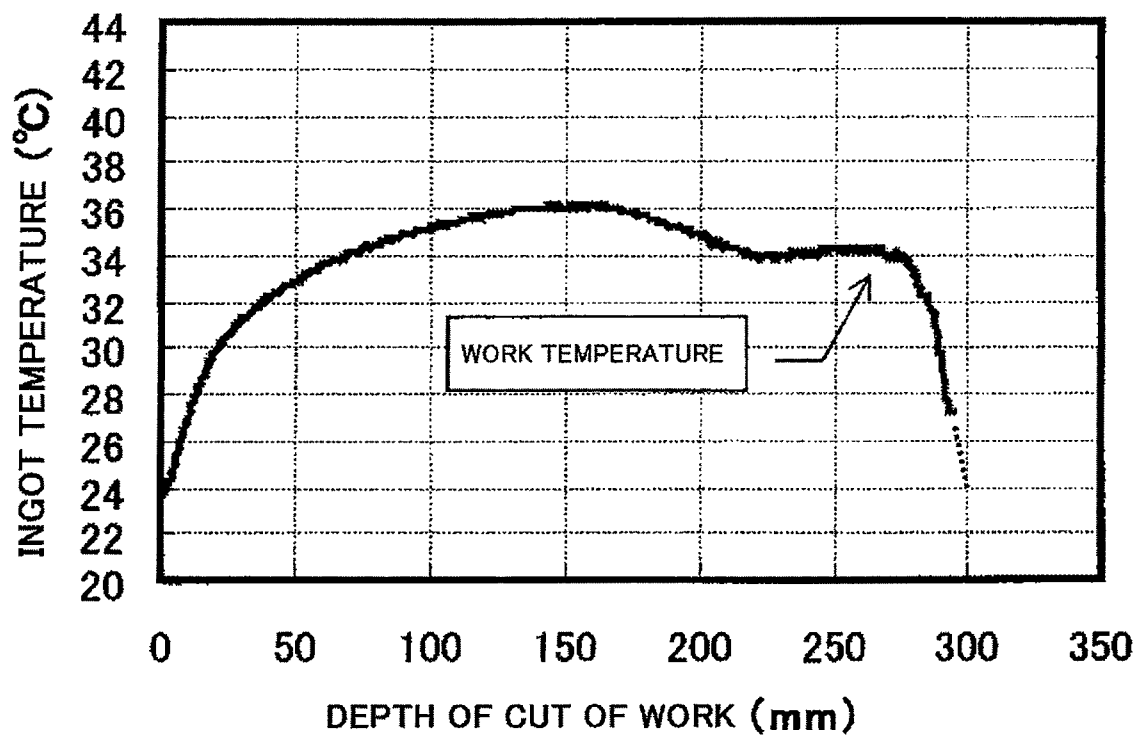
INFLUENCE OF INGOT
THERMAL EXPANSION



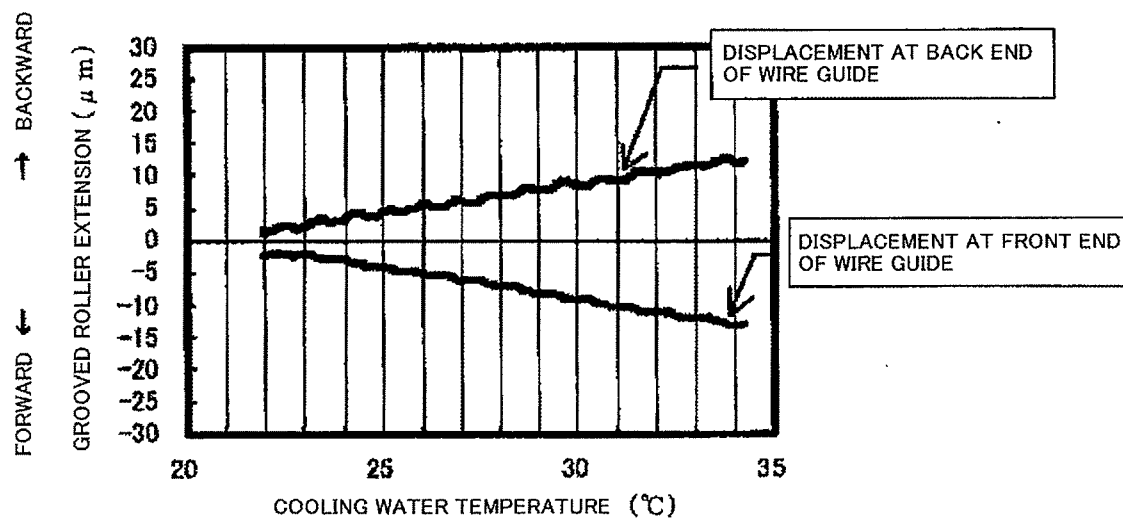
SHAPE OF BOW/WARP IN
WAFER



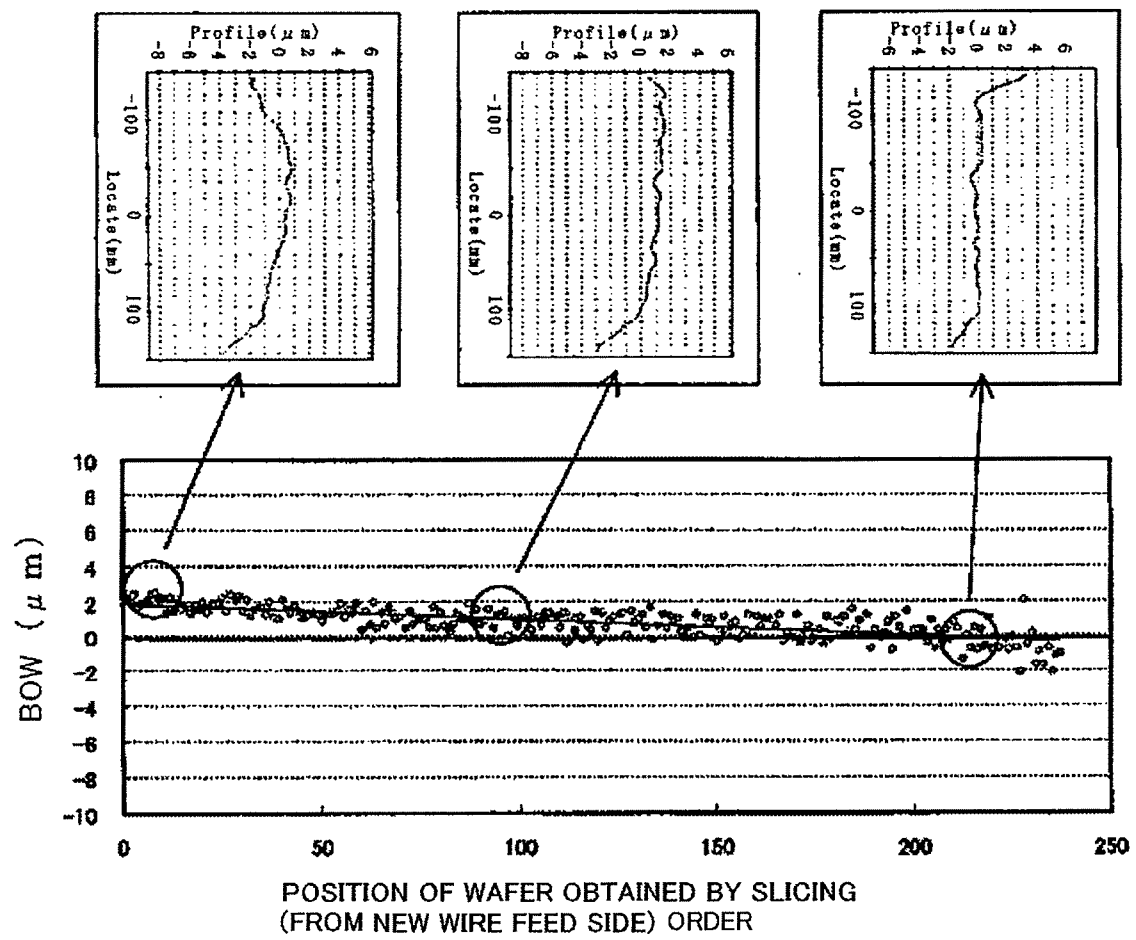
[FIG. 6]



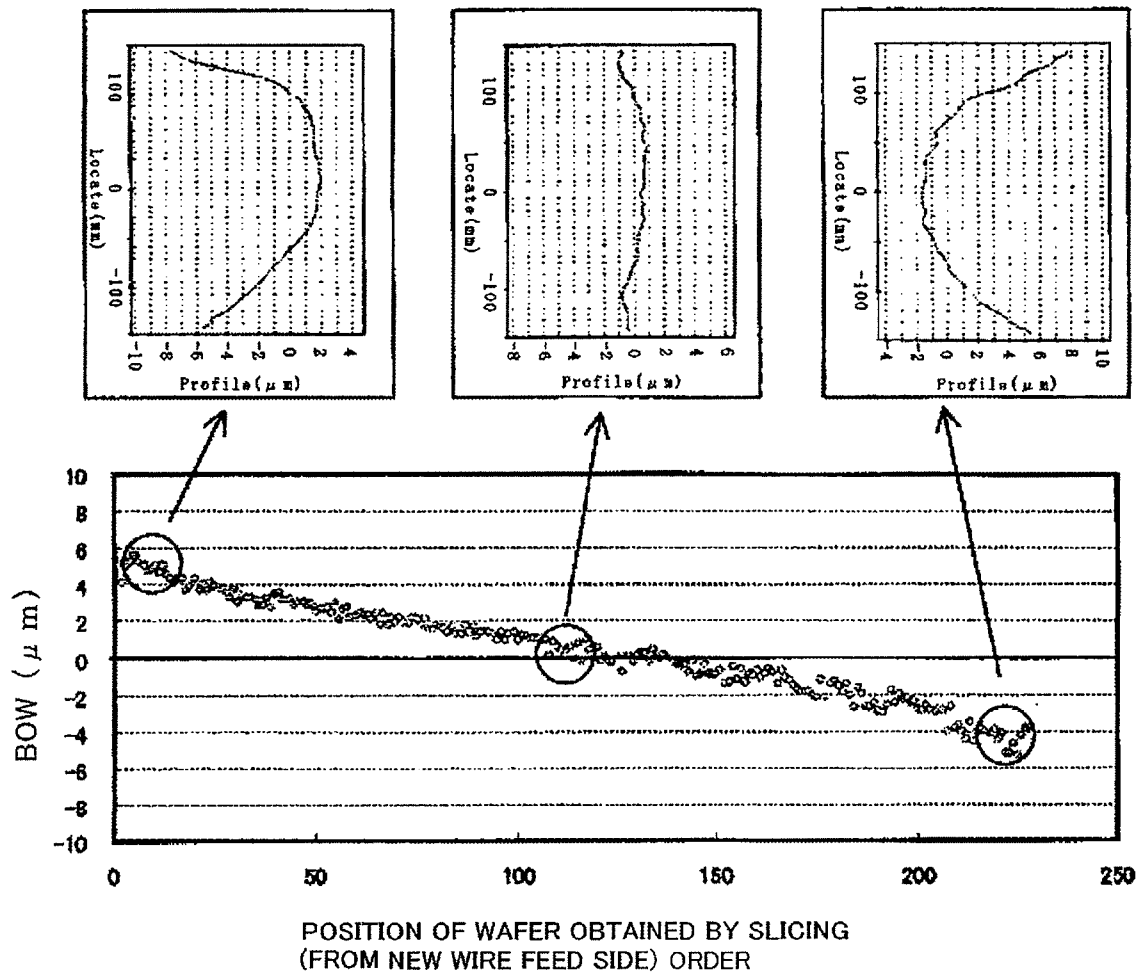
[FIG. 7]



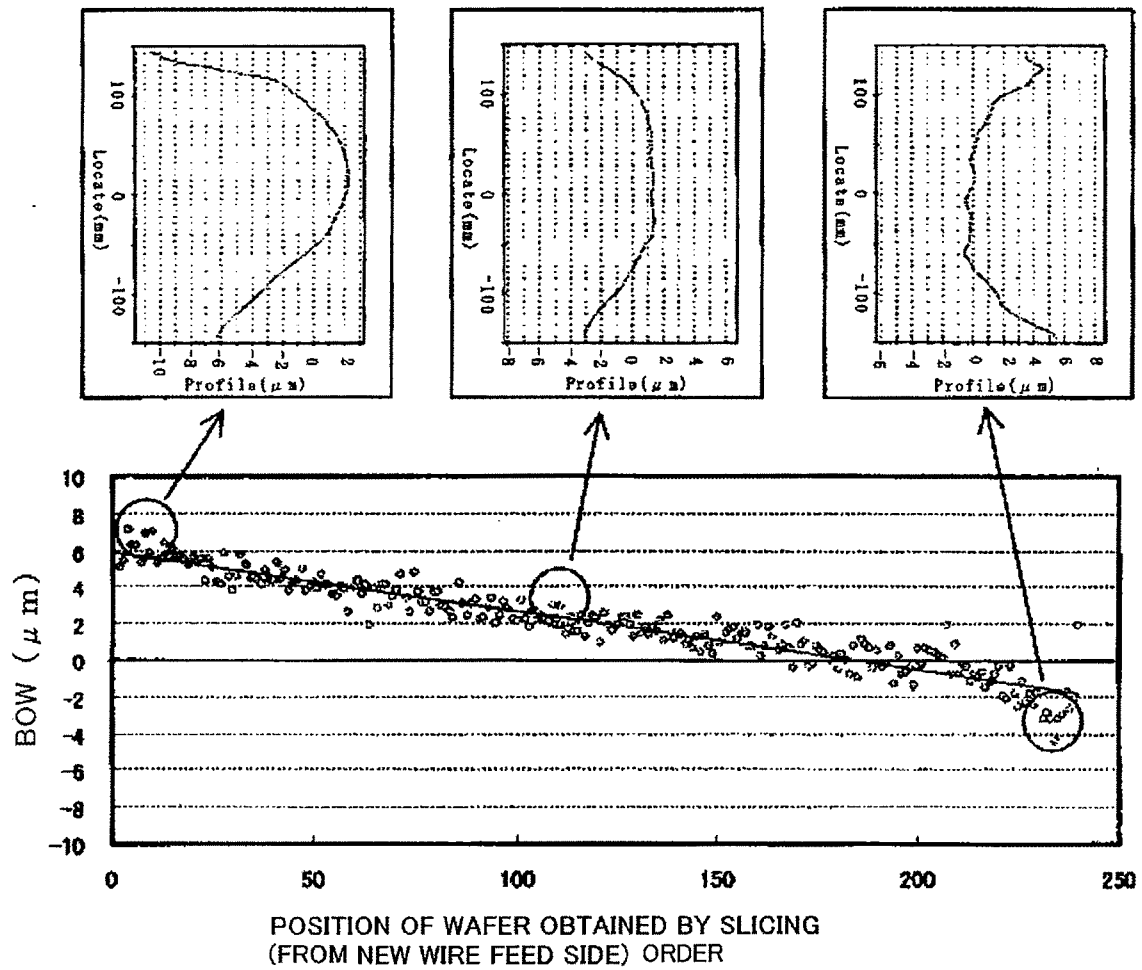
[FIG. 8]



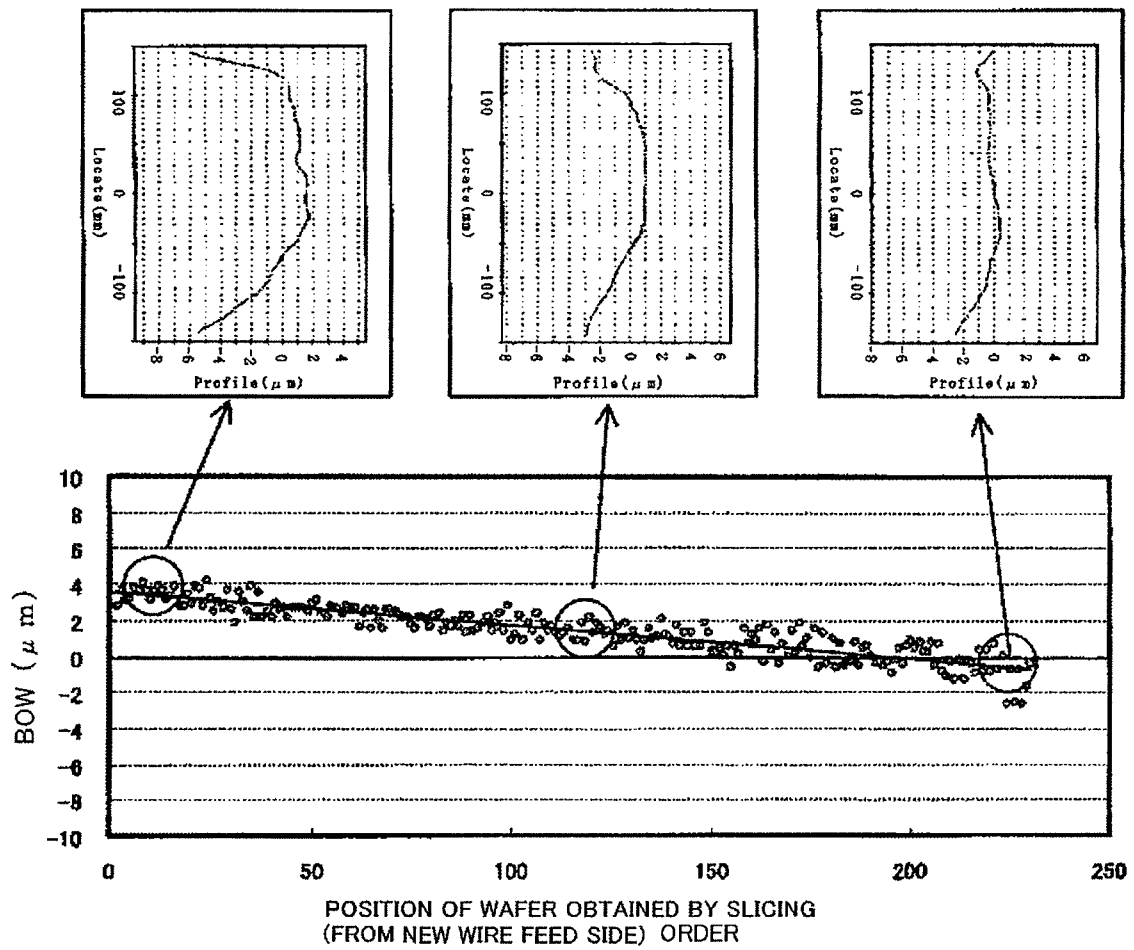
[FIG. 9]



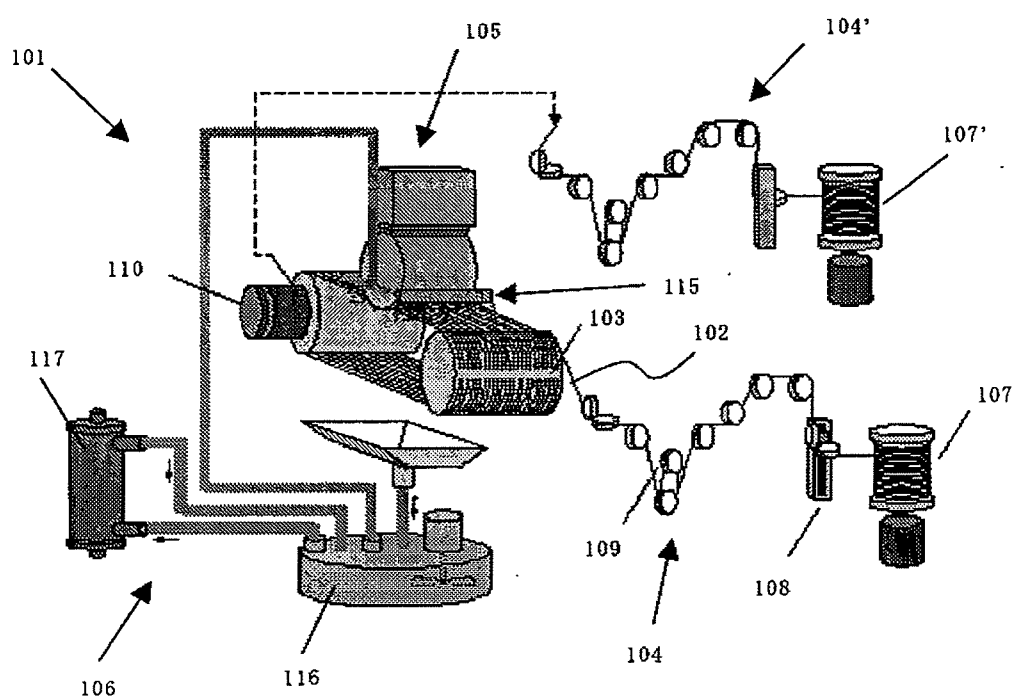
[FIG. 10]



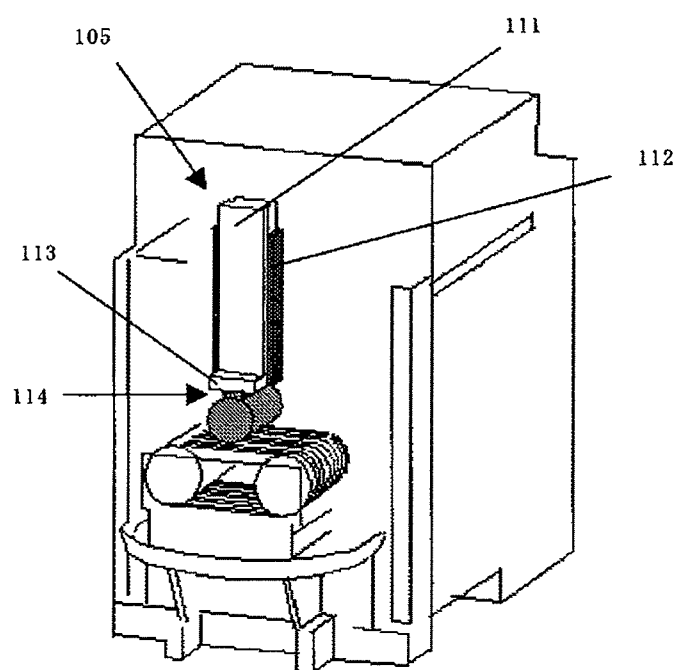
[FIG. 11]



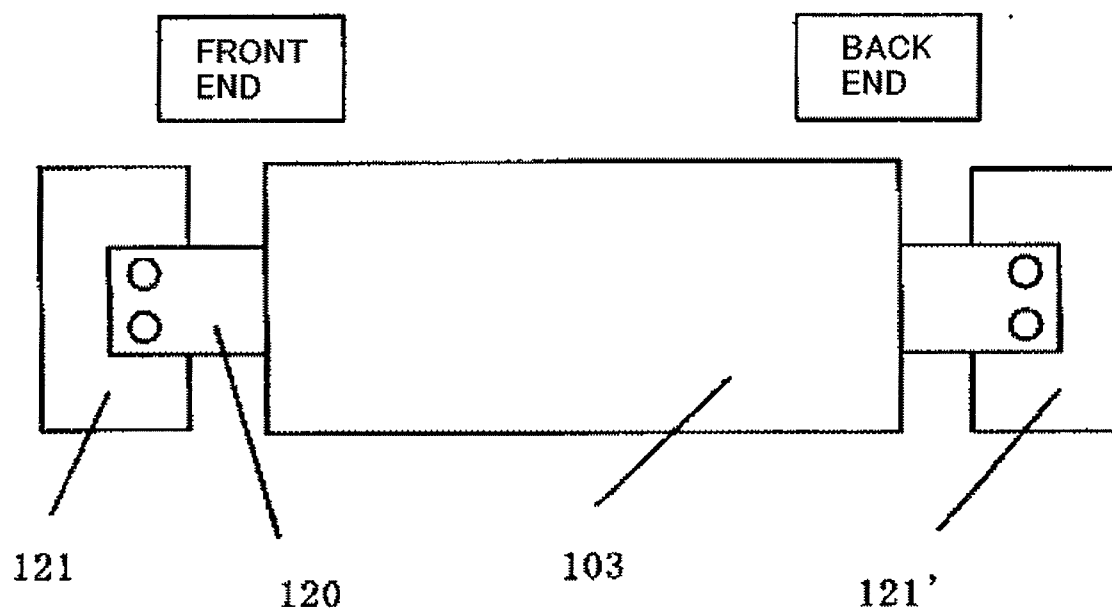
(A)



(B)

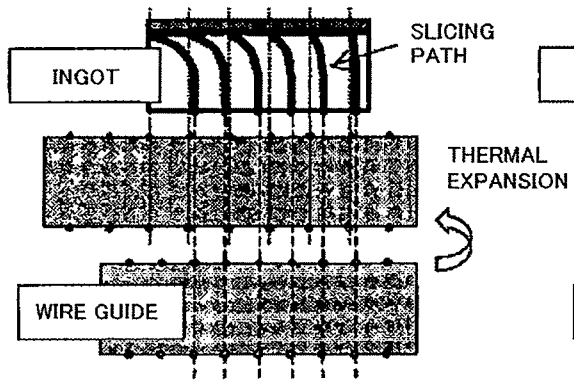


[FIG. 13]

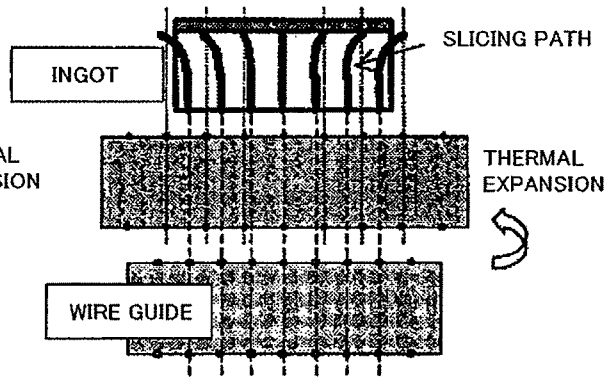


[FIG. 14]

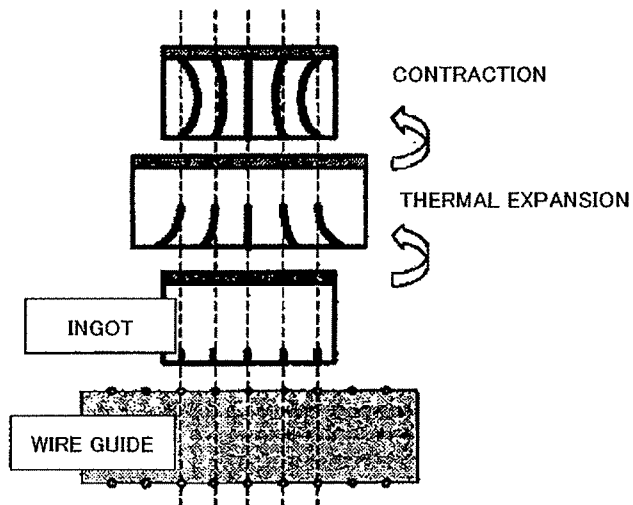
(A)



(B)



(C)



[FIG. 15]

